

L Number	Hits	Search Text	DB	Time stamp
1	33011	ceramic adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:44
2	737	printing adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:44
3	78	(ceramic adj substrate) and (printing adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:47
4	23533	electric adj connection	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:47
5	2	((ceramic adj substrate) and (printing adj electrode)) and (electric adj connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:48
6	413556	laminated	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:49
7	4125	removing adj film	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:49
8	8	(ceramic adj substrate) and laminated and (removing adj film)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:50
9	2268	29/25.35.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:51
10	0	((ceramic adj substrate) and laminated and (removing adj film)) and 29/25.35.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:51
11	1778	29/830.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:51
12	2225	29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:52
13	159	29/830.ccls. and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:52
14	0	(29/830.ccls. and 29/832.ccls.) and ((ceramic adj substrate) and laminated and (removing adj film))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:52
15	0	(29/830.ccls. and 29/832.ccls.) and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:52
16	426	310/326.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:53
17	499	310/322.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:53

18	25	310/326.ccls. and 310/322.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:53
19	0	(310/326.ccls. and 310/322.ccls.) and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:53
20	1082	310/334.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:53
21	0	310/334.ccls. and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:54
22	443	156/89.11.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:54
23	0	156/89.11.ccls. and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:54
24	0	156/89.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:54
25	0	310/89.6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:55
26	0	310/89.6	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:55
27	1495	427/58.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:55
28	5	427/58.ccls. and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:55
29	598	427/79.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:56
30	1	427/79.ccls. and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:56
31	0	428/292.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:56
32	191	264/618.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:56
33	1	264/618.ccls. and ((ceramic adj substrate) and (printing adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/22 09:57